

a solderable electrically conductive metal formed on at least one exposed surface of said conductive vias and in electrical contact therewith,
wherein at least one end of the plurality of conductive vias includes contacts adapted to be soldered to an electronic device or a substrate.

23. (Amended) A solderable flexible adhesive interposer comprising:

a plurality of layers of flexible dielectric adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi);

a plurality of conductive vias through each of said layers of flexible dielectric adhesive, said plurality of conductive vias being of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi), said conductive vias in an exposed one of said plurality of flexible dielectric adhesive layers being in a pattern adapted for connection to contacts of an electronic device or a substrate;

a solderable electrically conductive metal formed on an exposed surface of said conductive vias of the exposed one of said flexible dielectric adhesive layers and in electrical contact therewith, wherein at least one end of the plurality of conductive vias includes contacts adapted to be soldered to an electronic device or a substrate;

said plurality of conductive vias in each said layer of flexible dielectric adhesive being in a pattern corresponding at least in part to a pattern of said plurality of conductive vias of the adjacent layers of said flexible dielectric adhesive; and

a conductor residing between at least two of said adjacent layers of flexible dielectric adhesive, wherein said conductor is patterned and is in electrical contact with ones of said conductive vias of each of the at least two of said layers of flexible dielectric adhesive.

31. (Amended) A panel of a plurality of electronic devices having a pattern of contacts thereon and solderable flexible adhesive connections formed on the contacts comprising: